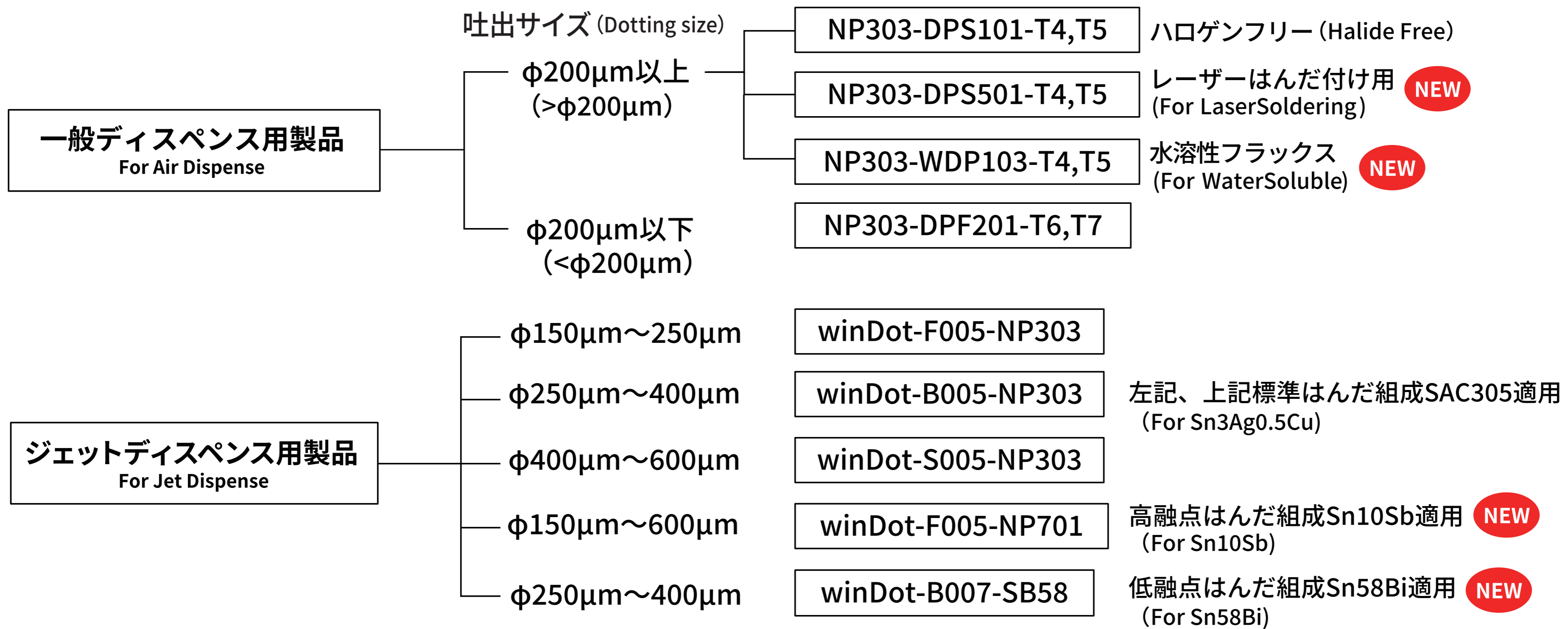


# 3D構造組立へ! 微細ディスペンス用はんだペースト!

For 3D structural assembly! Solder paste for micro-dispensing!

## ディスペンス用製品のラインアップ拡大 New solder paste for dispensing



### winDot-F005-NP701 (ジェットディスペンス用) (for Jet Dispensing)

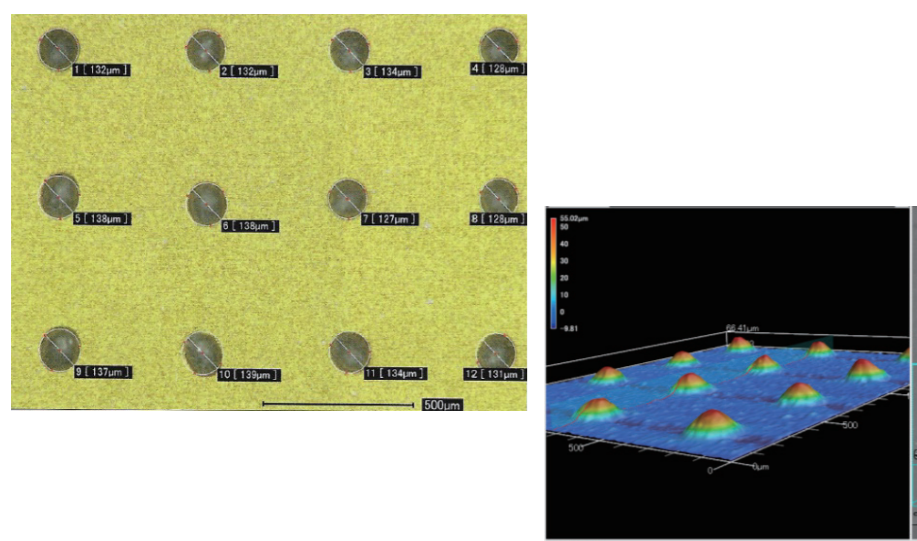
Jet Dispense 用はんだに高融点組成のはんだ (Sn10Sb) が新たに追加

High temperature solder (Sn10Sb) also added on line-up of Jet Dispense products

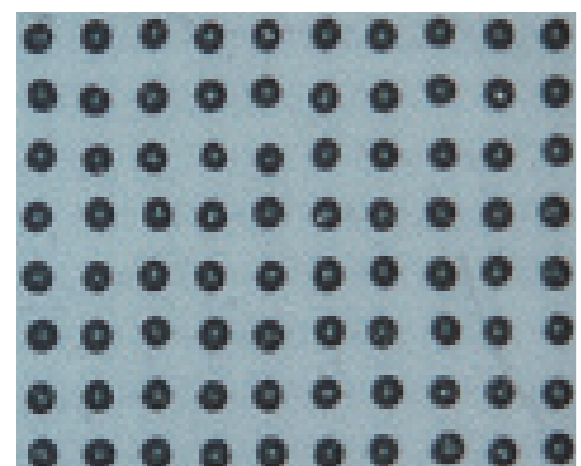
#### 微細吐出の特性 Property of fine dispense

Type7ペーストで φ200μm 以下の安定吐出を実現

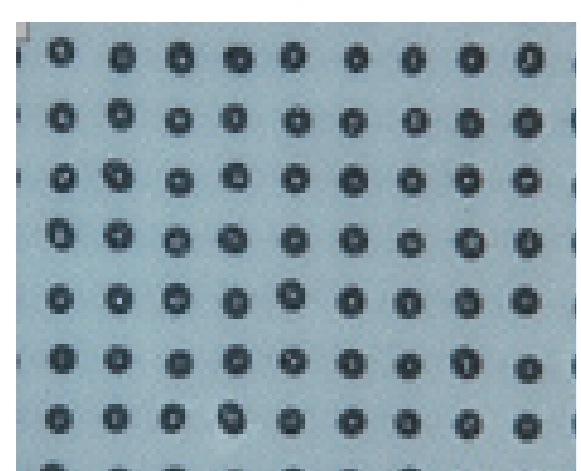
Capable of dispensing φ200μm or less by Type7 paste!



#### 連続吐出性能 Continuous dispensing performance



初期  
Initial stage



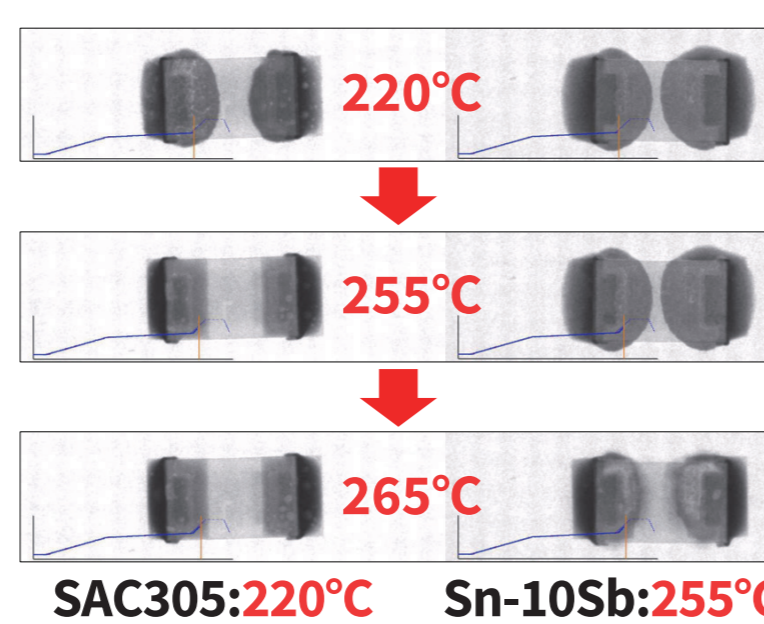
30万点  
300,000dot

#### 高融点はんだの特性 Property of high temperature solder

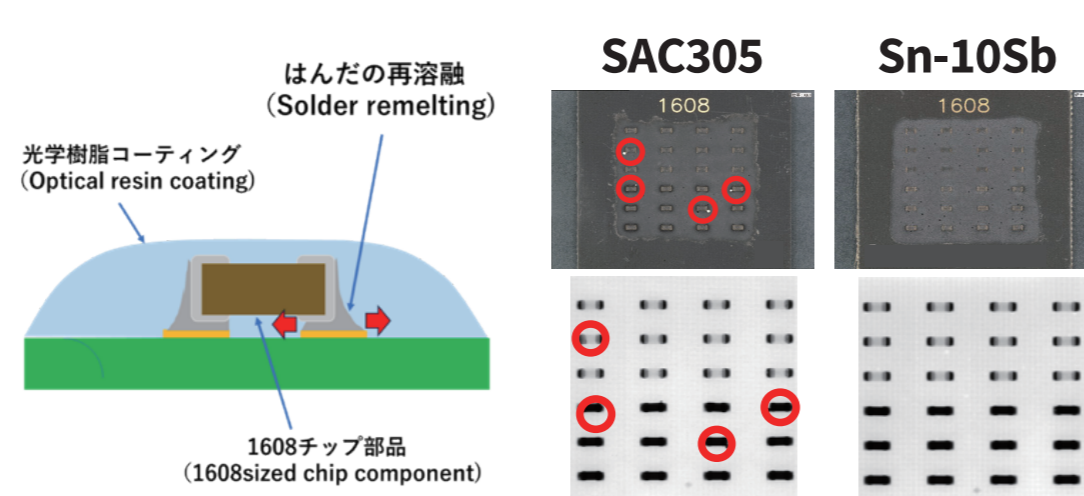
次工程での部品内部接合の再溶融防止に高融点はんだを適用

Apply high temperature solder to prevent from re-melting inside component at next process

#### 溶融開始温度比較 Melting temperature comparison



接合部の樹脂モールド後の再加熱によるはんだ再溶融挙動有無を確認  
Check the re-melting after resin molding



再加熱後にはんだの移動が確認された部分を赤枠で表示

Movement of solder can be seen in red circles

### NP303-WDP103-T5

(一般ディスペンス用：水溶性フラックス適用製品)  
(Water soluble flux based product For Air Dispensing)

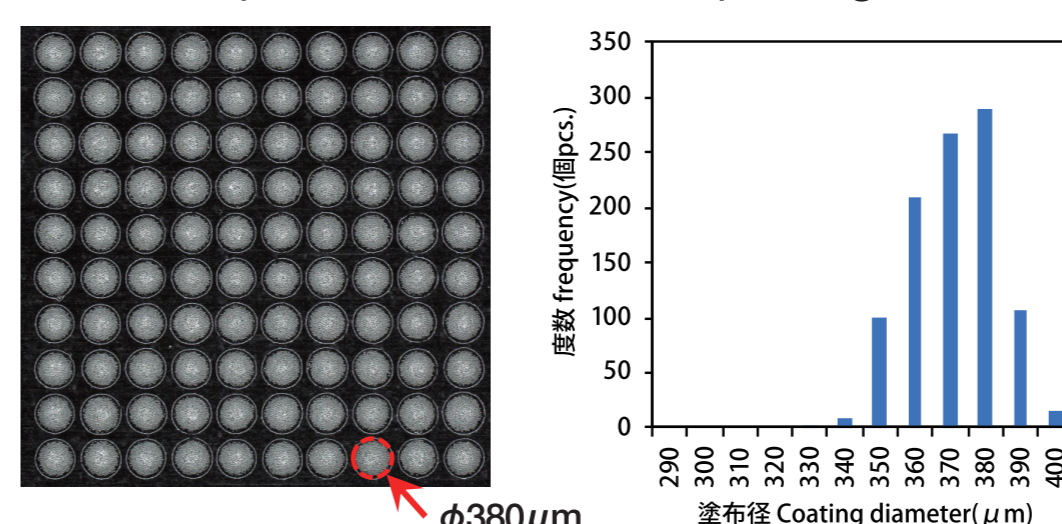
良好な吐出安定性と洗浄性

Excellent dispensing stability and cleanability

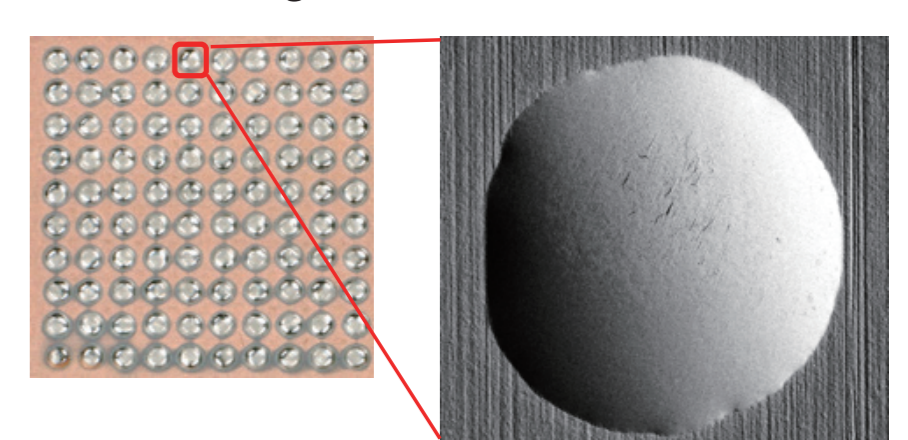
#### 吐出性と洗浄性の確認結果

Test result of dotting performance and washability

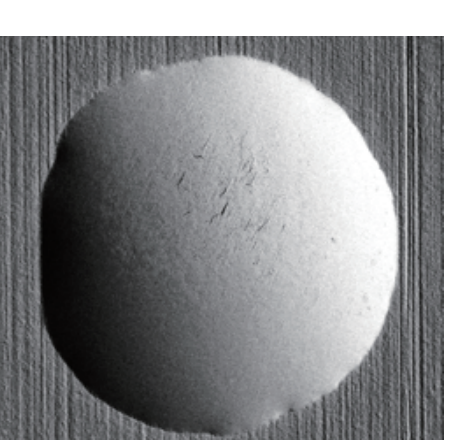
#### 60万点連続吐出時 At 600,000 points of continuous dispensing



#### 洗浄後 After washing



#### SEM観察 SEM observation

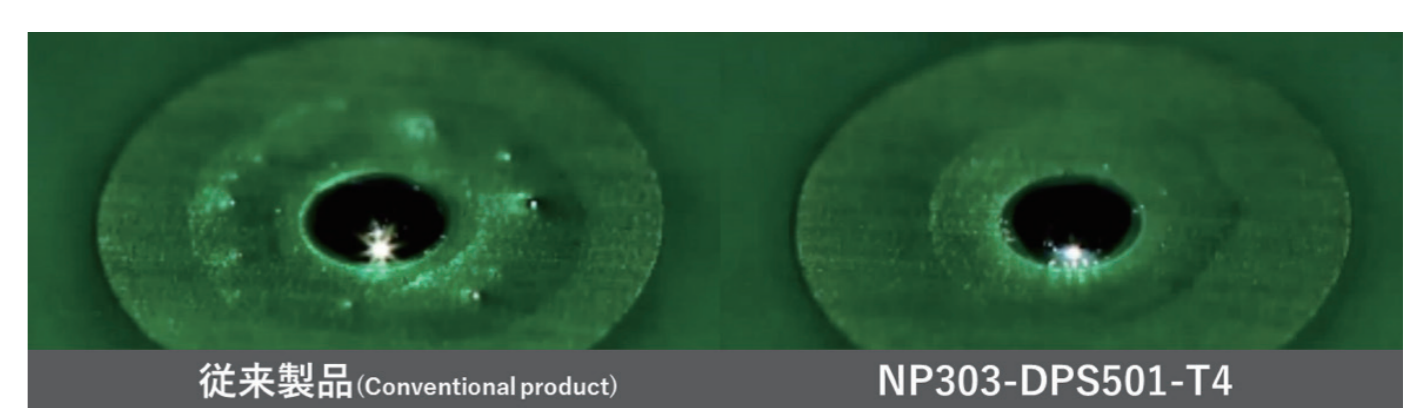
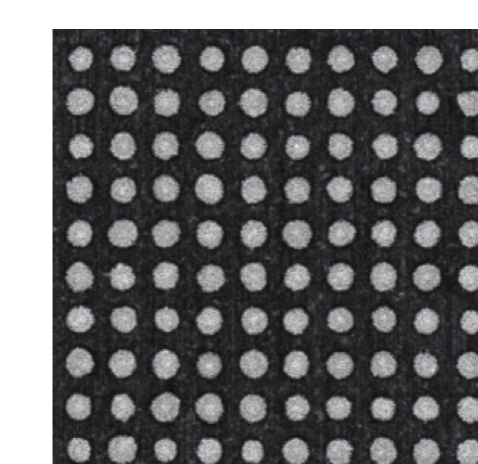


### NP303-DPS501-T4

(一般ディスペンス用：レーザーはんだ付け対応)  
(For normal dispense : applicable to laser soldering)

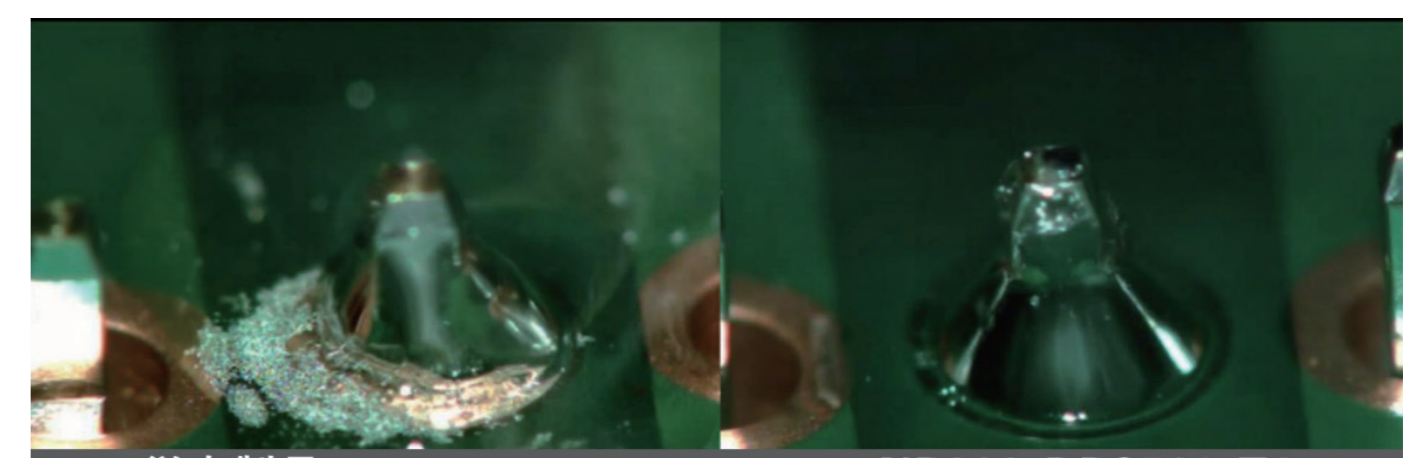
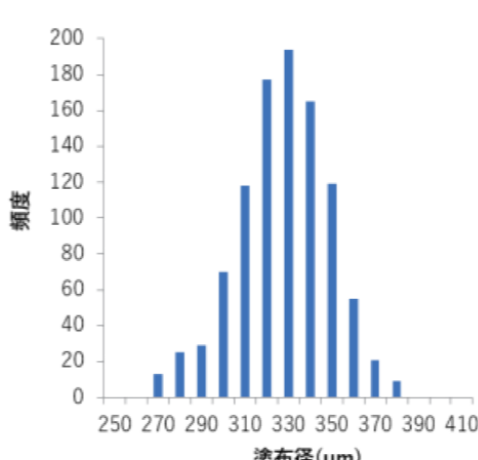
レーザー急加熱時のこぼれボール抑制で優れた凝集性

Excellent solderability with reduced solder ball outflow during rapid laser heating



従来製品 (Conventional product)

NP303-DPS501-T4



従来製品 (Conventional product)

NP303-DPS501-T4

